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DESCRIPTION

Description

BACKGROUND OF THE INVENTION

[0001] The present invention relates generally to "smart" cards and, more particularly, relates to smart cards which have at least one metal layer and are capable of radio frequency transmission (RF) and physical electrical interfacing. In particular, the invention relates to dual interface (i.e., capable of contactless and/or contact operation) smart cards having a metal layer and a rich and aesthetically pleasant appearance.

[0002] Smart cards are highly desirable and are in wide use, including: in payment and ticketing applications, such as mass transit and motorway tolls; in personal identification and entitlement schemes on regional, national, and international levels; in citizen cards; in drivers' licenses; in patient card schemes; and in biometric passports to enhance security for international travel.

[0003] A smart card is a card that includes embedded electronic circuitry such as an integrated circuit (IC) chip that can be either: (a) a secure microcontroller, also referred to as a microprocessor, or equivalent intelligence device with internal memory; or (b) a memory chip alone. A smart card connects or couples to a card reader with direct physical contact and/or with a remote contactless radio frequency interface.

[0004] There are three general categories of smart cards of interest. They are referred to herein as (1) contact, (2) contactless and (3) dual interface. (1) A "contact" smart card includes an IC chip connected to a conductive contact plate on which are mounted a number of physical contact pads (typically gold plated) located generally on the top surface of the card. A contact smart card must be inserted into a contact type smart card reader and transmission of commands, data, and card status takes place over the physical contact pads. (2) A "contactless" smartcard contains an IC chip and a card antenna by means of which RF signals are coupled between the smart card's chip and the antenna of a card reader. This permits wireless (e.g., RF) communication between the card and a card reader with no direct electrical contact between the card and the card reader. A contactless smart card requires only close proximity to a reader. Both the reader and the smart card have antennae, and the two communicate using radio frequencies (RF) over a contactless link. Most contactless cards also derive power for the internal chip from electromagnetic signals emitted by the card reader. The range of operation may vary from less than an inch to several inches. (3) A "dual-interface" smart card has, typically, a single IC chip (but could have two) and includes both contact and contactless interfaces. With dual-interface cards, it is possible to access the IC chip(s) using a

contact and/or a contactless interface.

[0005] It is desirable to make dual interface smart cards which can provide "contactless" and/or "contact" capability. It has also become very desirable and fashionable to make cards with one or more metal layers. A metal layer provides a desirable weight and a decorative pattern and/or reflective surface enhancing the card's appearance and aesthetic value. This is especially desirable for use by high-end customers. It is therefore desirable to make dual interface (contacts and contactless) smart cards having a metal layer.

[0006] However, several problems arise in the making of dual interface ("contactless" and "contact") smart cards with a metal layer because of conflicting requirements. By way of example, to construct a dual interface smart card, the contact pads associated with the IC chip need to be located along an external surface (top or bottom, but normally top) of the card to make contact with a contact card reader and the IC chip will generally be located near the top surface. However, any metal layer in the card interferes with radio-frequency (RF) communication signals (e.g., attenuates) between the card and the reader, and this could render the contactless smart card useless. So, a dual interface smart card with a metal layer needs to solve the problem of RF interference with respect to the IC chip. Compounding the problem is the requirement that the dual interface metal smart card have a highly sophisticated appearance. Due to the prestige and aesthetic aspect of these cards it is desirable that there be no perceptible depression or bump along the surface of the card, except for the contact pads.

[0007] WO 2013/110625 A1 for example describes a dual-interface smart card having a booster antenna with coupler coil in its card body, and a metallized face plate having a window opening for the antenna module. The window opening is substantially larger than the antenna module, providing perforations through the face plate, disposing ferrite material between the face plate and the booster antenna. A compensating loop is disposed under the booster antenna, offsetting the antenna module with respect to the coupler coil, arranging the booster antenna as a quasi-dipole, providing the module antenna with capacitive stubs, and disposing a ferrite element in the antenna module between the module antenna and the contact pads.

[0008] US 2015/021403 A1 deals with a dual interface smart card, wherein a conductive coupling frame has two ends, forming an open loop having two ends or a discontinuous metal layer disposed surrounding and closely adjacent a transponder chip module, and substantially coplanar with an antenna structure in the transponder chip module. A metal card body or a transaction card with a discontinuous metal layer having a slit or a non-conductive strip extending from a module opening to a periphery of the card body to function as a coupling frame.

SUMMARY OF THE INVENTION

[0009] The invention is defined in the independent claims. Further advantageous

embodiments are defined in the dependent claims.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] The invention will be understood more completely from the following detailed description of presently preferred, but nonetheless illustrative, embodiments in accordance with the present invention, with reference being had to the accompanying drawings, which are not drawn to scale, but in which like reference characters denote like components; and

Figure 1 is a simplified, isometric diagram of a smart card 10 with a metal layer 30, embodying the invention;

Fig. 1A is a highly simplified, idealized isometric diagram of an integrated circuit (IC) module capable of contactless and contact operation intended for use in making smart cards embodying the invention;

Fig. 1B is a simplified idealized cross sectional diagram of the IC module of Fig. 1A used in the card shown in Fig. 1;

Figure 2 includes cross sectional diagrams of various processing steps (1 through 7) to form a card embodying the invention;

Fig. 3A is a simplified cross sectional diagram of a card being made as shown in step 5 of Fig. 2;

Fig. 3B is a top view of a card being formed as shown in Fig. 3A with a plug (34) and the opening (36) formed in the plug;

Fig. 3C is a top view of the top layer of a card embodying the invention formed in accordance with the process shown in Fig. 2;

Fig. 4 includes cross sectional diagrams of various processing steps (1 through 5) to form a card according to another aspect of the invention;

Fig. 5A is a cross sectional diagram corresponding to step 4 of Fig. 4 showing a plug and openings formed in the plug prior to insertion of an IC module;

Fig. 5B is a top view of a card having the cross section shown in Fig. 5A showing the plug and openings formed in the plug prior to insertion of an IC module formed in accordance with Fig. 4;

Fig. 5C is a top view of a card formed according to the process steps shown in Fig. 4 and as shown in Figs. 5A and 5B with an IC module inserted in the opening for the module; and

Fig. 6 is a cross-sectional diagram showing a masking layer formed on a card such as the one shown in Fig. 5C.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0011] An integrated circuit (IC) module 7 having multiple contacts as shown in Fig. 1A is to be mounted in, and on, a card 10 as shown in Fig. 1 with the top surface of the IC module and its contacts generally flush with the top surface of the card. By way of example it is shown that the length, width and depth of the card may respectively be approximately 85.6 mm (3.37 inches) by 54.0 mm (2.125 inches) by 0.76 mm (0.03 inches). For purpose of illustration and the discussion to follow assume, as shown in Fig. 1A, that the IC module has a depth D1, a length L1 and a width W1. Modules such as IC module 7 are commercially available, for example, from Infineon or NXP. The lateral dimensions of some of these modules were approximately 1.32 mm (0.052 inches) by 12 mm (0.47 inches) with a depth ranging from 0.13 mm (0.005 inches) to more than 0.64 mm (0.025 inches). These dimensions are purely illustrative and IC modules used to practice the invention may be greater or smaller in size.

[0012] As shown in Fig. 1B, IC module 7 contains an internal microprocessor chip 7a, a chip antenna 7b and a contact pad 7c. Pad 7c may be a conventional multi-contact pad used in contact-type smart cards and is positioned to engage contacts in a contact card reader (not shown) when the smart card is inserted therein. An epoxy blob 7d encapsulates the bottom side of the IC module. The epoxy blob allows the IC module to be easily attached (e.g., by gluing) to an underlying surface.

[0013] As noted above, the invention is directed to the manufacture of a smart metal card having dual interface capability and also having a top surface which is free of any bumps or depressions, except for: (a) the IC module and its contacts, and/or (b) any design or texture intentionally formed on the top surface. In accordance with the invention, a card can be made to have a highly aesthetic, smooth and visually pleasing appearance even though the card must include dual interface capability (i.e., contact and contactless capability). That is, smart cards having a metal layer as a top surface, for aesthetic reasons, must include an IC module and its associated contacts. For the card to be used in a contact mode, the contacts of the IC module have to be located along an exterior surface of the card. Typically, the contacts are located along the top surface of the card; although the contacts could conceivably be located along the bottom surface of the card. To enable effective wireless (RF) transmission there has to be a cut out (opening) in the metal layer underlying and surrounding the IC module. A challenge is to produce these cut outs (openings) in the metal layer without affecting the smooth, aesthetic, exterior (e.g., top) appearance of the card.

[0014] A method of forming a card in accordance with the invention includes the structure and processing steps illustrated in Fig. 2.

1. 1- A metal layer 30 is selected which is intended to serve as the top layer of a card 10 (as shown in step 1 of Fig. 2). The metal layer 30 has a top (front) surface 301 and a

bottom (back) surface 302; the front and back surfaces are generally parallel to each other. The thickness (D) of the metal layer 30 may range from less than 0.025 mm (0.01 inches) to more than 0.51 mm (0.02 inches). In one embodiment the metal layer 30 was made of stainless steel and its thickness was 0.4 mm (0.0155 inches). Metal layer 30 may, by way of example and not by way of limitation, be selected to be iron, tantalum, aluminum, brass, copper or any alloy or compound thereof.

2. 2- A pocket 32 is formed along the underside of layer 30. It may be referred to as a reverse pocket formed starting from the bottom surface of metal layer 30 (as shown in step 2 of Fig. 2). The pocket 32 may be formed in any known manner including, but not limited to: milling, casting, 3D printing, laser cutting, water jet electro- discharge (EDM). The pocket 32 has a top 321 which ends a distance (or thickness) D1 below top surface 301, where D1 is typically equal to (or nearly equal to) the depth of the IC module 7. The depth (thickness) D2 of pocket 32 is then equal to (D-D1) inches. D2 will generally always be set to equal the depth D of the metal layer 30 minus the thickness D1 of the IC module used to form the card. The pocket 32 may be of regular or irregular shape, a rectangular solid or a cylinder whose planar projection in the horizontal plane may be a square, a rectangle or a circle. The lateral dimensions [length (L2) and width (W2)] of the pocket 32 can be, respectively, equal to or greater than the lateral dimensions [length L1 and width W1] of the IC module as further discussed below. In the embodiments L2 and W2 are shown to be, respectively, greater than L1 and W1, but that is not a necessary condition.
3. 3- A plug 34 of any material which does not substantially interfere with RF transmission (e.g., any non-metallic material, or even a material such as tungsten or a composite thereof) is formed or shaped to conform to the dimensions of the milled pocket 32 and is inserted in the pocket to fill the milled (cut out) region (as shown in step 3 of Fig. 2). As discussed below the plug functions to electrically isolate and insulate the IC module from the metal layer and to also physically secure the IC module. The interior of the pocket 32 and/or the exterior of the plug 34 is/are coated with a suitable adhesive (e.g., such as acrylic or acrylic modified polyethylene, cyanoacrylate, silicone elastomer, epoxy) so the plug 34 adheres firmly to the walls of the pocket throughout the processing of the metal layer in the formation of the card. The plug 34 may be made of any thermoplastic material such as PET, PVC or other polymer or any material such as curable resin or epoxy or a ceramic or even of tungsten material which does not significantly impede radio frequency (RF) transmission.
4. 4- As shown in step 4 of Fig. 2, an adhesive layer 42 is used to attach a ferrite layer 44 to the back surface 302 of layer 30. The ferrite layer 44 is placed below the metal layer 30 to act as a shield (reflector) to prevent/reduce metal layer 30 from interfering with radio frequency radiation to and from the smart card. Ferrite layer 44 decreases the "shorting" effect of metal layer 30 for enabling transmission or reception via antenna 47. Those skilled in the art will appreciate that it would also be possible to form or lay out the ferrite material in a different manner.
Also, an adhesive layer 46 is used to attach a plastic (e.g., PVC) layer 48 which contains and/or on which is mounted a booster antenna 47. Layer 48 may be made of PVC or polyester and may be between 0.025 and 0.38 mm (.001 and .015 inches) thick. The

windings of booster antenna 47 may range from less than 80 microns to more than 120 microns in diameter and may be secured to layer 48 by ultrasonic welding or heating the wire prior to placing it in contact with the plastic layer or by any other suitable process. A layer 52 which includes a signature panel and a magnetic stripe may be attached to layer 48 before or after lamination. Layers 42, 44, 46, 48 (and possibly 52) may be formed as a sub-assembly 40 and attached to the bottom side 302 of metal layer 30.

5. 5- The assembly comprising layers 30, 42, 44, 46 and 48 is laminated (as indicated in step 5 of Fig. 2) to form a card assembly 50.
6. 6- A hole (or opening) 36 is then formed (e.g., by milling) through the metal 30 to a depth D1 from the top surface and, concurrently, a hole 362 is then formed in plug 34, (e.g., by drilling about the center of the plug 34) and through the underlying layers 42, 44 and 46 until layer 48, as shown in step 6 of Fig. 2. The lateral dimensions of hole 36 formed in the metal layer 30 are designed to correspond to the dimensions L1 and W1 of the IC module 7 so the IC module can be inserted in the hole (opening) 36. The lateral dimensions of the hole 362 formed in the plug 34 will be L3 and W3, where L3 and W3 are less than L1 and W1. So made, plug ledges 341a will provide support for the IC module and keep it at its designed height of D1 below the top card surface. The IC module can be snugly inserted and attached to the sides of opening 36 and to top 341a of the plug 34. That is, the IC module can be inserted with tight clearance and glued in place. The smaller hole (opening) 362 formed below hole 36 accommodates the rear (bottom) end of module 7. Hole 362 extends vertically down through ferrite layer 44 and is made sufficiently wide to enable RF signals to pass between antenna 47 and the chip antenna 7b.

With respect to the operation of the card, booster antenna 47 is designed to capture radio frequency energy generated by an associated card reader (not shown) and to communicate with the card reader. By design, module antenna 7b is sufficiently close to couple inductively with antenna 47, thereby providing signals from antenna 47 to chip 7a, while keeping the chip electrically isolated from antenna 47. In operation, ferrite layer 44 shields metal layer 30, to make it possible for radio frequency radiation to enter and be emitted from card 10. In operation, ferrite layer 44 shields metal layer 30, to make it possible for radio frequency radiation to enter and be emitted from card 10. Booster antenna 47 is designed to capture radio frequency energy generated by an associated card reader (not shown) and to communicate with the card reader. By design, module antenna 7b is sufficiently close to couple inductively with antenna 47, thereby providing signals from antenna 47 to chip 7a, while keeping the chip electrically isolated from antenna 47.

7. 7- As shown in Step 7 of Fig. 2, an IC module 7 which, as shown in Fig. 1B, includes a chip 7a, a chip antenna 7b and a set of contacts 7c is positioned within hole 36. The IC module 7 is glued in place completing the formation of a card embodying the invention. To appreciate the appearance of the card as finally formed reference is first made to Fig. 3A (which is essentially a copy of step 6 of Fig. 2) and to Fig. 3B. Fig. 3B is a top view of the card being formed showing the openings (36 and 362) formed in the metal and the plug. Note the hole 36 in metal layer 30 will have edge(s) 361 and the hole 362 in the plug and the underlying layers 42, 44, 46 will have edge(s) 345/ 367. The portion of the

plug 34 below region 341b and the outer edge 343 of the plug will not be seen. Hence outer edge 343 is shown with dashed lines.

The resultant Fig. 3C is a top view of a card 10 showing the module 7 mounted and inserted in the top of the card. The plug 34 is not seen since it is underneath the metal layer. Thus, the top surface of a card 10 formed in accordance with the process steps shown in Fig. 2 displays a completely smooth unbroken metal surface (except for the contact pad of the IC module). The underlying plug is covered (hidden) by an overlying metal region. Significantly, the card having the desired beautiful physical appearance can function as a wireless (contactless) card or as a contact card.

[0015] The dimensional tolerances of the various holes/openings and of the components need to be close enough so that on a platen lamination all parts fuse together with no airspace or sinks in the outward appearance of the card.

[0016] As shown in the Figures, metal layer 30 has a cut out 36 formed in its top surface. The thickness/depth D1 of cut out 36 is made substantially equal to the depth of the IC module 7. The hole/opening 36 is machined through metal layer 30 dimensioned to receive module 7, which is secured therein, as by bonding. Module 7 contains a microprocessor chip 7a (internally), a chip antenna 7b and a contact pad 7c. Pad 7c is a conventional contact pad used in contact-type smart cards and is positioned to engage contacts in a card reader when the smartcard is inserted therein.

[0017] By design, plug 34 is substantially wider than module 7. Preferably, plug 34 extends at least 0.04 laterally beyond either side of module 7. This prevents the metal in substrate 30 from interfering with communication between the card and chip. However, the plug does not have to be wider than module 7 (i.e., its lateral dimensions need not be greater than those of the module).

[0018] Module 7 is positioned vertically within metal layer 30 so as to provide a contact pad 7c along the top metal surface to realize the contact functions of the dual interface. Moreover, positioning module 7 on plug 34 which is made larger (though not necessarily so) in area than the module 7 makes it possible to decrease interference in the radio communication between module antenna 7b and the booster antenna 47.

[0019] Although preferred embodiments of the invention have been disclosed for illustrative purposes, those skilled in the art will appreciate that many additions, modifications, and substitutions are possible without departing from the scope of the invention

[0020] Alternatively, cards embodying the invention may be formed as shown in Figs. 4, 4A, 5A, 5B, 5C and 6. These cards differ from those discussed above in that a plug is formed whose thickness is equal to the thickness of the metal layer. That is, there is no recessed pocket. As shown in Fig. 4, a card formed in accordance with this aspect of the invention may

include the following processing steps and structure:

1. 1- A metal layer 30 is selected (as shown in step 1 of Fig. 4) which is intended to serve as the top layer of a card 10. The metal layer 30 has a top (front) surface 301 and a bottom (back) surface 302 and a thickness (D) which may range from less than 0.25 mm (0.01 inches) to more than 0.5 mm (0.02 inches). Metal layer 30 may have the same characteristics and properties as metal layer 30 shown and discussed above.
2. 2- A hole 420 of depth D is formed in the metal layer 30 (as shown in step 1 of Fig. 4). The lateral dimensions of the hole are L2 and W2 (see Figs. 5A and 5B). The hole 420 may be formed in any known manner (e.g., casting or milling). The hole 420 may be a regular or irregular solid cube, or a cylinder whose planar projection in the horizontal plane may be a square, a rectangle or a circle or an irregular shape. In the embodiment shown in Fig. 4, the lateral dimensions [length (L2) and width (W2)] of the hole 420 are respectively greater than the lateral dimensions [length L1 and width W1] of the IC module as further discussed below. Generally, L2 is greater than L1 (by at least 1 mm (0.04 inches) and W2 is greater than W1 (by at least 1 mm). However, as noted above, L2 may be made equal to L1, and W2 may be made equal to W1. The advantage of making L2 and W2, respectively, larger than L1 and W1 is to provide greater separation between the metal layer and the IC module and thus enhance RF transmission and reception.
3. 3- A plug 434 of any material like plug 34 which does not interfere with RF transmission is formed or shaped to conform to the dimensions of the hole 420 to fill the cut out region (as shown in step 2 of Fig. 4). Plug 434 is processed and functions to secure the IC module. The interior walls of the hole 420 and/or the exterior walls of the plug 434 is/are coated with a suitable adhesive so the plug 434 adheres firmly to the walls of the hole throughout the processing of the metal layer in the formation of the card. The plug 434 may be made of any thermoplastic material such as PET, PVC or other polymer or any material such as epoxy resins and a ceramic.
4. 4- As shown in step 3 of Fig. 4, an adhesive layer 42 is used to attach a ferrite layer 44 to the back surface 302 of layer 30. An adhesive layer 46 is used to attach a plastic (e.g., PVC) layer 48 which contains and/or on which is mounted a booster antenna 47 to the ferrite layer. Layers 42, 44, 46, and 48 and the booster antenna 47 are formed in a similar manner as the corresponding number components shown in Fig. 2 and serve the same or similar functions.
5. 5- The assembly comprising layers 30, 42, 44, 46 and 48 is laminated to form a card assembly 350 (as indicated in step 3 of Fig. 4).
6. 6- A T-shaped hole/opening 436 is then formed through the plug 434. The hole 436 is formed by milling, drilling and/or any other suitable means. The top portion 436a of T-shaped hole 436 is formed to have lateral and depth dimensions to accommodate the IC module. Where the dimensions of IC module 7 are L1 by W1 by D1 the top portion of 436a will be formed to be just about L1 by W1 by D1 to enable the IC module to be snugly inserted within the hole 436a and to be glued in place. The bottom portion 436b of the hole 436 formed in plug 434, (by drilling vertically down about the center of the plug 434) extends through the underlying layers 42, 44 and 46 and until layer 48, as

shown in step 4 of Fig. 4. The lateral dimensions of hole 436b formed in plug 434 are made large enough to enable sufficient RF signals to pass between booster antenna 47 and the IC chip module 7 to enable RF communication to take place reliably. The lateral dimensions of the hole 436b formed in the plug 434 are denoted as L3 and W3, where L3 and W3 are less than L1 and W1. Note that making L3 and W3 less than L1, and W1, respectively, results in the formation of ledges 438 which will provide support for the IC module and keep it at its designed height of D1 below the top card surface 301. The IC module 7 can be snugly inserted and attached (glued) to the ledges 438 and the top interior walls of the plug 434.

7. 7- As shown in Step 5 of Fig. 4, IC module 7 which includes a chip 7a and a chip antenna 7b and a set of contacts 7c is positioned within hole 436a is glued in place.

[0021] Fig. 5A is an enlarged cross sectional diagram corresponding to step 4 of Fig. 4. Fig. 5B is a top view of a card showing the holes formed in the metal and the plug. Fig. 5C is a top view of a card showing the module 7 mounted and inserted in the top of the card. The smart metal card 10 can function as a wireless (contactless) card or as a contact card. Note that as shown in Figs. 5A, 5B and 5C the hole portion 436a has an inner edge 440. The plug has an outer edge 442. As is evident from figs. 5B and 5C, the IC module 7 will cover openings 436a and 436b. As a result there is a space/area 450 between edges 440 and 442 extending around the outer periphery of the IC module between the module 7 and the metal layer 30. The space/area 450 may be objected to on aesthetic grounds as it detracts from the continuous metal layer (except for the necessary module contact pad). However, it should be appreciated that the space area 450 may enhance RF transmission. The presence of space/area 450 and any depression or bump related to space 450 may be masked by the addition of a masking layer 470, as shown in Fig. 6. This may be acceptable in many instances. However, in instances where such a solution is still not acceptable or feasible, the solution is to revert to making cards as per the process steps shown in Fig. 2.

[0022] Thus, a problem with the smart cards formed in accordance with the process shown in Fig. 4 is that a portion of a plug may be seen. The portion of the plug may mar the continuous appearance of the card and/or as a bump on the surface or as a depression. This may be so, even if a masking (concealing) layer 470 is formed over layer 30.

[0023] As taught and discussed with reference to Fig. 2, above, the spacing and any discontinuity in the metal surface (except for the IC module) are avoided by forming a recess pocket 32 in substrate 30 and filling the recess with a plug 34 which is not seen from the top of the card. Thus, In contrast to previous and other dual interface smart metal cards, the plug 34 does not appear as a bump on the surface or as a depression. It is not visible when the card is viewed from the outside. The process of Fig. 2 thus differs from the process of Fig. 4 where a through hole 420 is formed in the metal layer 30 and a plug 434 is formed which fills the hole 420.

[0024] However, it should be noted that in all the embodiments shown herein a plug is used to separate an IC module from a surrounding metal layer to promote RF transmission capability and the plug is also used to position and secure the IC module within the card. Openings for the plug and its positioning within the card are designed to maintain the exterior of the card flat and visually pleasant.

REFERENCES CITED IN THE DESCRIPTION

Cited references

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METAL SMART KORT MED DOBBELT GRÆNSEFLADE

Patentkrav

1. Et dobbeltgrænsefladekort (10) omfattende:

et metallag (30) med en første overflade (301) og en anden overflade (302), der strækker sig parallelt med hinanden;

en åbning (36, 420) i metallaget konfigureret til at modtage et stik (34, 434) dannet af ikke-RF-hæmmende materiale og et dual-interface integreret kredsløb (IC) modul (7), dual-interface IC-modulet har kontakter (7c) og omfatter RF-transmissionsmidler (7b) til at muliggøre kontakt og kontaktløs betjening af kortet; og

mindst et yderligere lag (42, 44, 46, 48, 52) stablet i forhold til proppen (34, 434), hvor åbningen er defineret af et første udskåret område (36) i den første overflade (301), det første udskårne område konfigureret til at modtage IC-modulet, og et andet udskåret område (32), der strækker sig fra den anden overflade (302) og strækker sig lodret fra den første overflade og symmetrisk i forhold til det første udskårne område (36), andet udskæringsområde konfigureret til at modtage stikket,

kendetegnet ved, at det første udskårne område (36) har et første område og en første omkreds, og det andet udskårne område (32) har et andet område og en anden omkreds, der er større end det første område og den første omkreds, hvor stikket (34, 434) har en omkreds, der er større end en omkreds af IC-modulet.

2. Dobbeltgrænsefladekort ifølge krav 1, hvor åbningen strækker sig fra den første overflade til den anden overflade.

3. Dual-interface-kort ifølge krav 1, kendetegnet ved, at der er dannet et lodret hul i proppen og gennem det yderligere lag, hvor det lodrette hul har et tredje areal og en tredje perimeter mindre end henholdsvis det første areal og den første perimeter.

4. Dobbeltgrænsefladekort ifølge krav 1, hvor metallaget (30) har en tykkelse D, og åbningen i metallaget strækker sig over tykkelsen D af metallaget (30).

5. Dobbeltgrænsefladekort ifølge krav 4, hvor tykkelsen D af metallet er større end en tykkelse D1 af IC-modulet.

6. Dobbeltgrænsefladekort ifølge krav 4, hvor IC-modulet (7) er monteret på stikket (434), og IC-modulet og stikket strækker sig mellem den første (301) og anden (302) overflade af metallet.

7. Dual-interface-kort ifølge krav 6, hvor proppen (434) udfylder åbningen i metallet, hvor proppen har et første stikudskæringsområde (436a), der strækker sig fra den første overflade til optagelse af IC-modulet (7) og et andet propudskåret område, der strækker sig fra den anden overflade af metallet.

8. Dual-interface-kort ifølge krav 7, yderligere indbefattende et maskeringslag (470), der strækker sig over en del af proppen placeret mellem åbningen og det første udskårne område.

9. Dobbeltgrænsefladekort ifølge et hvilket som helst af kravene 1-8, hvor metallet (30) omfatter et af rustfrit stål, jern, tantal, aluminium, messing, kobber eller en hvilken som helst legering eller forbindelse deraf.

10. Dual-interface-kort ifølge et hvilket som helst af kravene 1-9, hvor stikket (34, 434) omfatter et ikke-metallisk stof eller et metal, der ikke hindrer RF-transmission.

11. Dual-interface-kort ifølge et hvilket som helst af kravene 1-10, hvor kortet har en længde og bredde, og metallet strækker sig over hele kortets (10) længde og bredde.

12. Dual-interface-kort ifølge et hvilket som helst af kravene 1-11, hvor det mindst ene yderligere lag (48) omfatter en booster-antenne (47) til at forbedre RF-transmission med IC-modulet (7).

13. Dual-interface-kort ifølge krav 12, hvor booster-antennen er konfigureret til induktivt at koble til IC-modulet.

14. Dual-interface-kort ifølge et hvilket som helst af kravene 1-13, hvor det mindst ene yderligere lag omfatter et ferritlag (44).

15. Dual-interface-kort ifølge et hvilket som helst af kravene 1-14, hvor det mindst ene yderligere lag omfatter et signaturpanel og en magnetstribе.

16. Fremgangsmåde til fremstilling af dual-interface-kortet (10) ifølge et hvilket som helst af kravene 1-5, hvor fremgangsmåden omfatter trinene:

udvælgelse af metallaget (30);

udskæring af det andet udskårne område (32) i metallaget startende fra metallagets anden overflade;

sikkert at fastgøre proppen (34) dannet af ikke-RF-hindrende materiale inden for det andet udskårne område;

udskæring af det første udskårne område (36) i den første overflade af metallaget anbragt symmetrisk i forhold til det andet udskårne område;

indsættelse og sikker fastgørelse af dual-interface IC-modulet (7) inden for det første udskårne område med kontakter (7c) af dual-interface IC-modulet placeret langs et samme vandrette plan som den første overflade af metallaget.

17. Fremgangsmåde til fremstilling af kortet ifølge krav 7, hvor fremgangsmåden omfatter trinene:

udvælgelse af metallaget (30);

dannelse af åbningen (420);

sikker fastgørelse af proppen (434) inden i åbningen; og

fastgørelse af et ferritlag (44) til bundoverfladen af metallaget;

dannelse af det første propudskårne område (436a) i proppen (434); og

indsættelse af IC-modulet (7) inden i og sikker fastgørelse af IC-modulet inden for det første stikudskæringsområde (436a).

18.Fremgangsmåde ifølge krav 17, yderligere omfattende dannelse af det andet propudskårne område (436b) i proppen (434) og det mindst ene yderligere lag (42, 44, 46), idet det andet propudskårne område har et første område og en første omkreds henholdsvis mindre end et andet område og en anden omkreds af IC-modulet.

19.Fremgangsmåde ifølge krav 17 eller 18, yderligere indbefattende dannelse af et maskeringslag (470), der strækker sig over en del af proppen (434), der strækker sig mellem åbningen (420) og det første propudskårne område (436a).

20.Fremgangsmåde ifølge et hvilket som helst af kravene 17-19, yderligere omfattende at laminere metallaget og det ene eller flere yderligere lag sammen.

21.Fremgangsmåde ifølge et hvilket som helst af kravene 16-20, yderligere omfattende at fastgøre et signaturpanel og magnettribelag (52) til et yderste lag af det ene eller flere yderligere lag.

22.Dual-interface-kort ifølge krav 1, hvor en yderligere åbning (362) strækker sig ind i stikket (34, 434) og danner mindst én stikafsats (341a), hvorpå IC-modulet er monteret.

23.Dual-interface-kort ifølge krav 22, hvor den yderligere åbning (362) strækker sig gennem stikket (34, 434).

DRAWINGS

Drawing

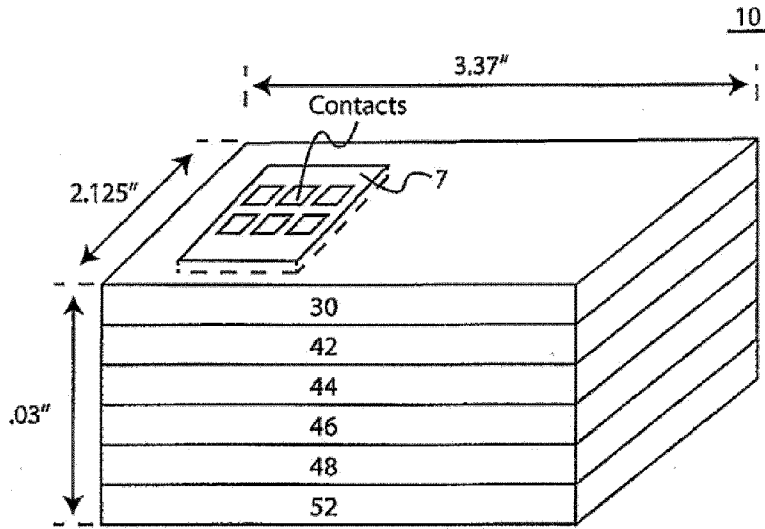


FIG. 1

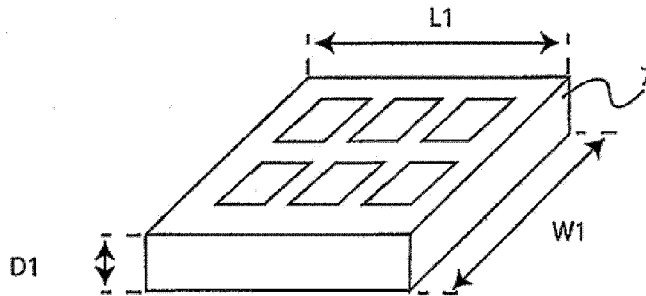


FIG. 1A

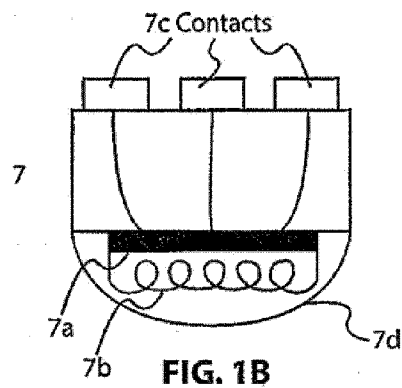


FIG. 1B

FIG. 2

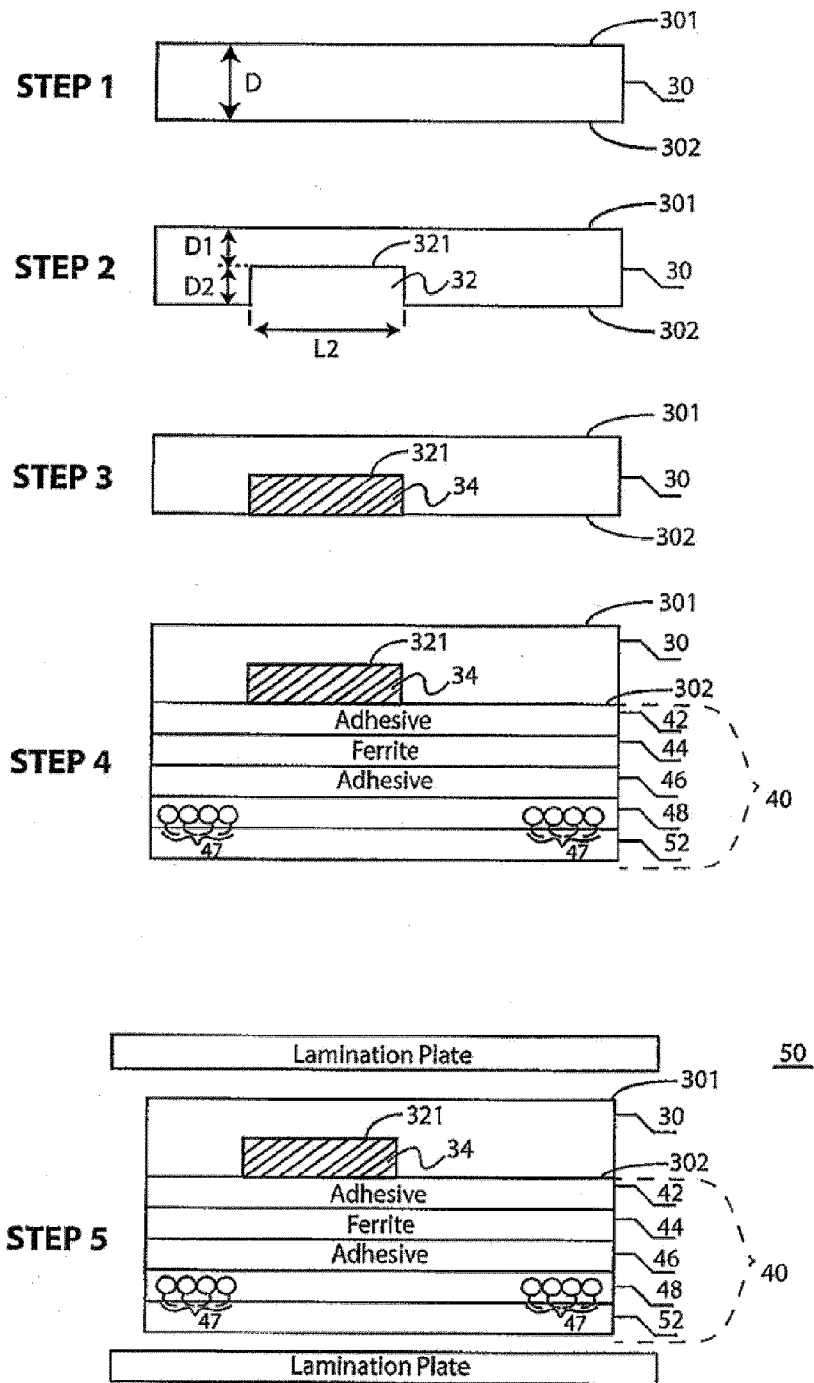
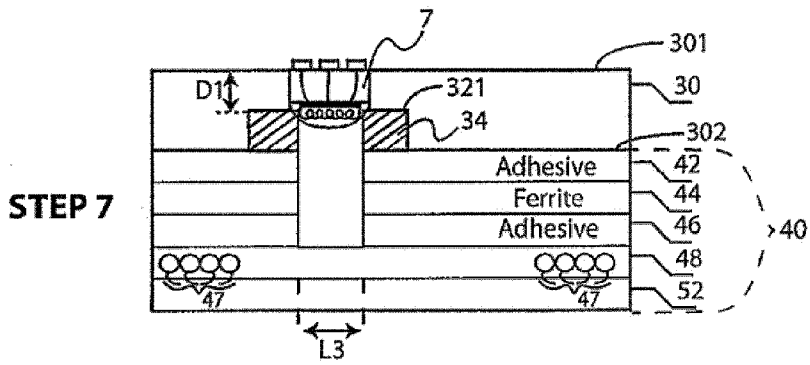
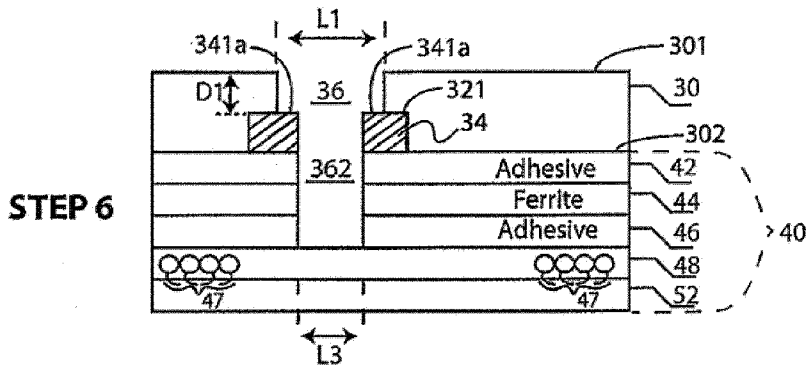


FIG. 2 cont.



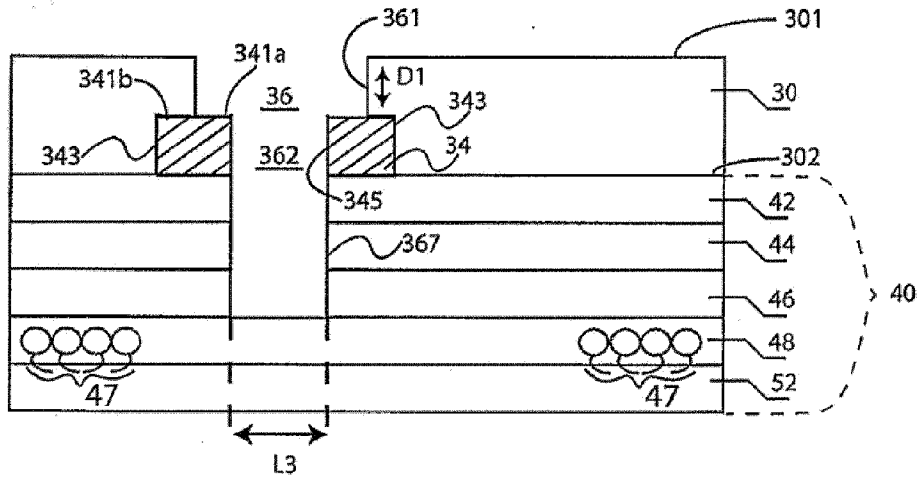


FIG. 3A

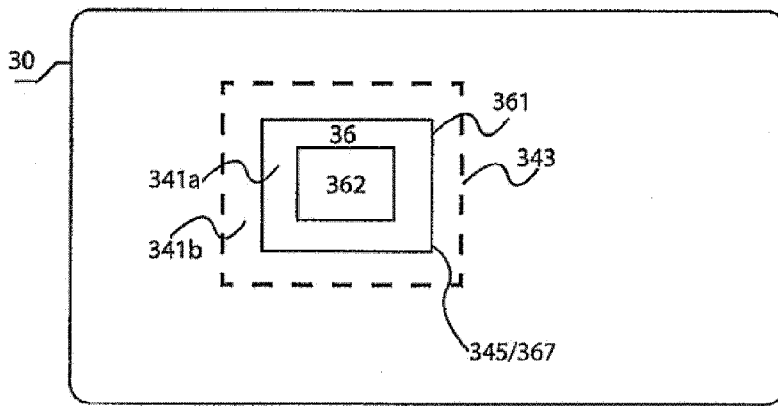


FIG. 3B

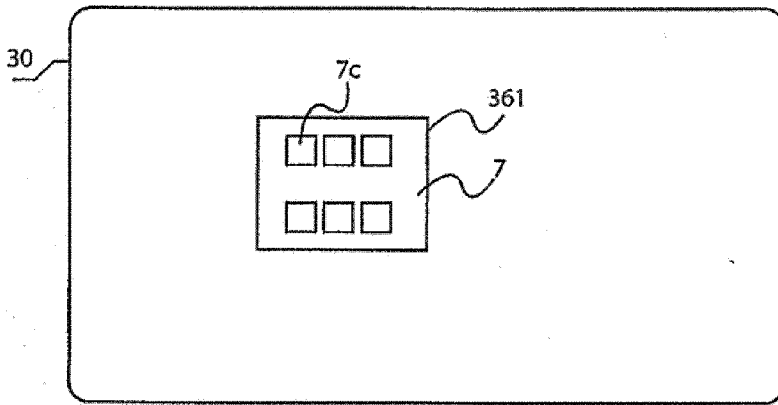
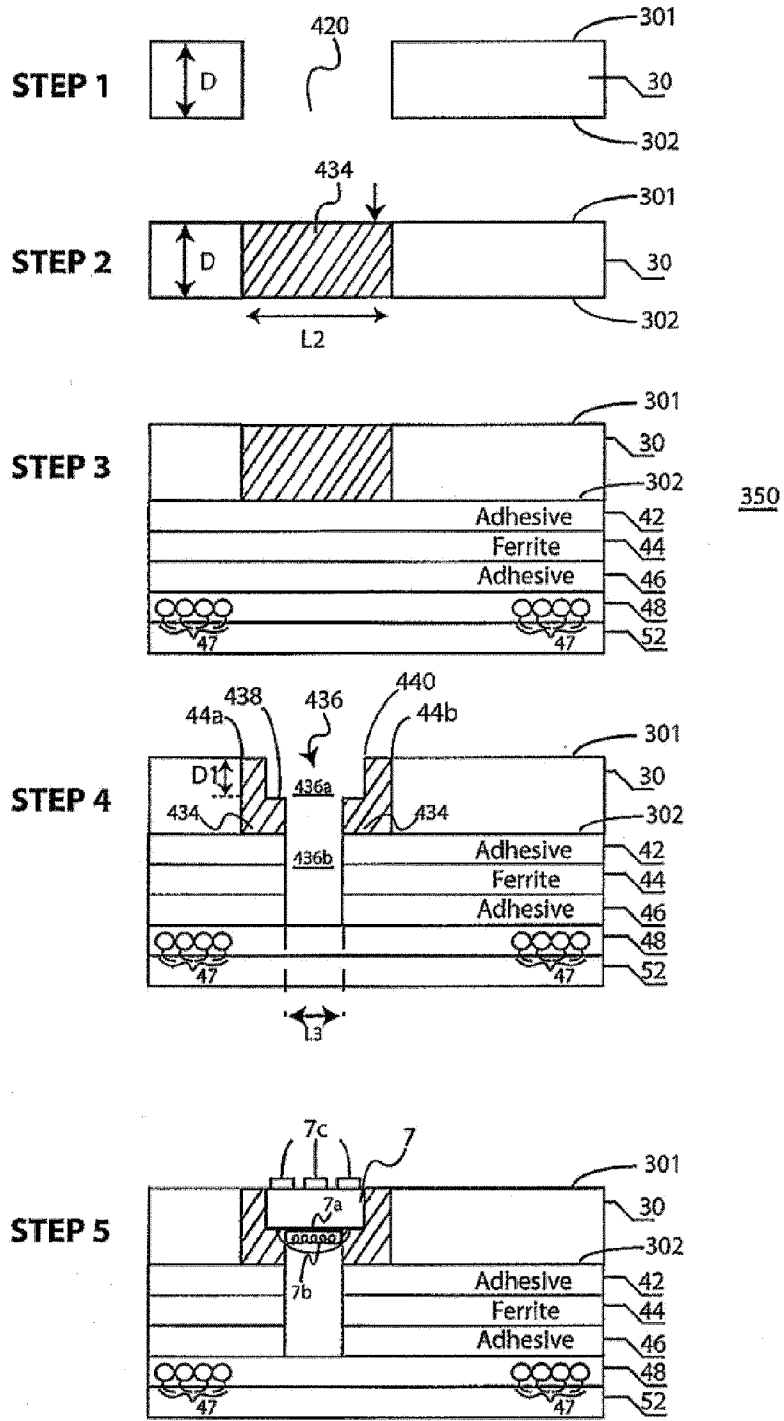


FIG. 3C

FIG. 4



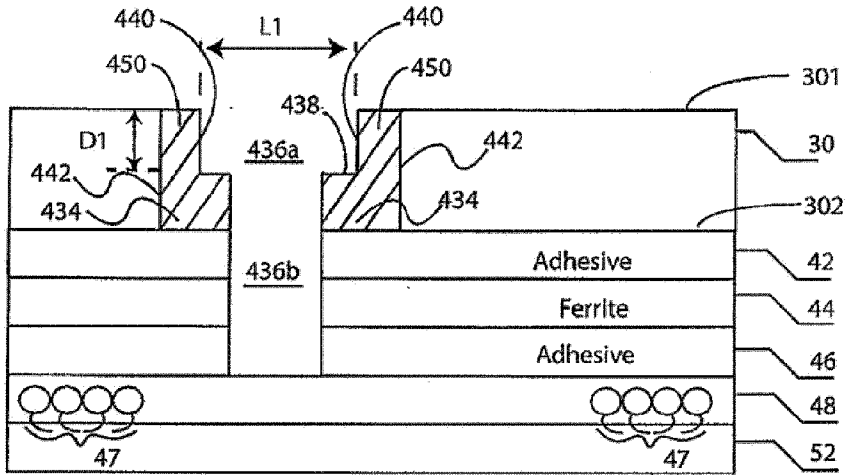


FIG. 5A

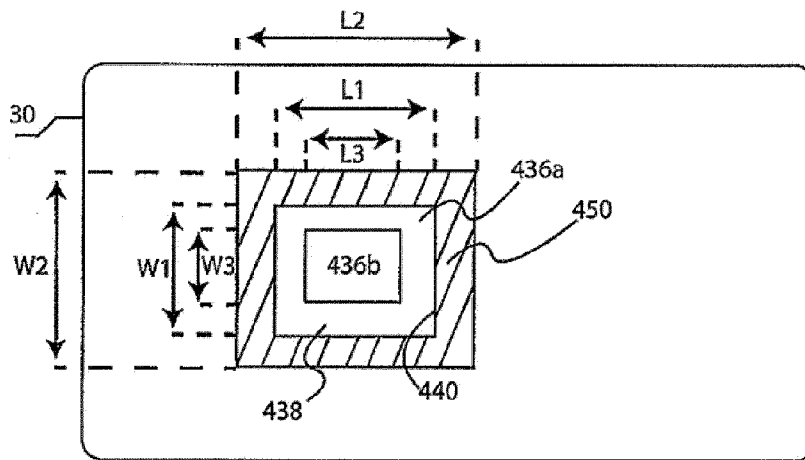


FIG. 5B

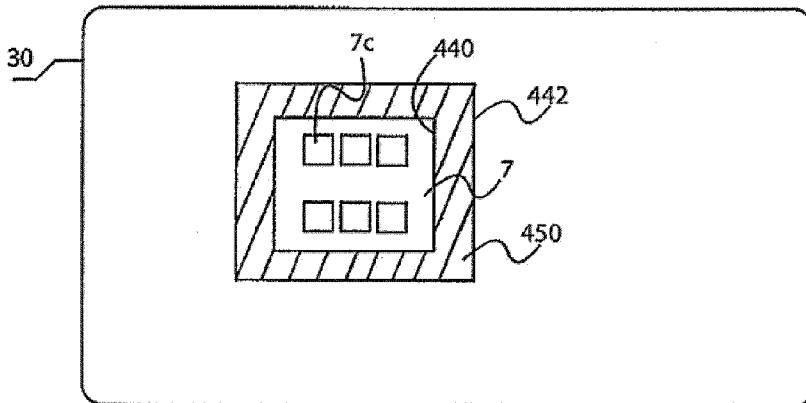


FIG. 5C

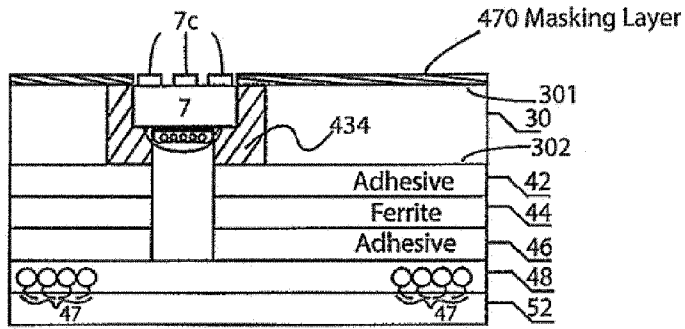


FIG. 6